| ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Par | PC. Bannockl   | burn, Illinois, A      | ll rights reserved untions. | under both          | This docume<br>level parts, t   | ent is a declaration en declaration | on of the su<br>compasses           | bstances v<br>all lower | vithin the manufactu<br>level materials for v | rer listed which the r | tem. Note:<br>nanufacture       | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|--|--|------------------------|-----------------------------|---------------------|---|---|-------------------------------------|-------------------------|---|------------------------|---------------------------------|---|---------------------------------|--|
|  | 21.1 IPC Web Site for Information on IPC-1752 Standard Form Distribution Distributi |                        |                             |                     | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials a |   |                                     |                         | ials and N                                    | lfg Informa            | tion                            |   |                                 |  |
| upplier Information  |  |                        |                             |                     |   |   |                                     |                         |   |                        |                                 |   |                                 |  |
| Company name* Company  |  |                        | any unique ID               |                     |   | Unique ID Authority   |                                     |                         |   | Respon                 | Response Date*                  |   |                                 |  |
| nsemi  |  |                        |                             |                     |   |   |                                     |                         | 2023-06-08                                    |                        |                                 |   |                                 |  |
| tact Name Title - Contact  |  |                        |                             |                     | Phone - Contact*  |   |                                     |                         | Email - Contact*                              |                        |                                 |   |                                 |  |
| Product-Env-Stewards Product Enviro  |  |                        | ro Compliance               |                     | NA  |   |                                     |                         | Product-Env-Stewards@onsemi.com               |                        |                                 |   |                                 |  |
| Authorized Representative* Title - Represen                                |  |                        | entative                    |                     | Phone - Representative*   |   |                                     | Email - Representative* |   |                        |                                 |   |                                 |  |
| Product-Env-Stewards Product En  |  |                        | Enviro Compliance           |                     |   | NA  |                                     |                         |   | Produ                  | Product-Env-Stewards@onsemi.com |   |                                 |  |
| Requester Item Number  | Mfr Iten   | n Number               | Mfr Item Name               |                     |   | Effective Date  | tive Date Version Manufacturing Sit |                         | Ianufacturing Site                            |                        | Weight*                         | UOM                                       | Unit Type                       |  |
|  | NC7SV(   | NC7SV02P5X ULP-A 2-1   |                             | -A 2-Input NOR Gate |   | 2023-06-08  |                                     | C                       | CNS   |                        | 5.842                           | mg  | Each                            |  |
| Ianufacturing Proccess Informa   | tion   |                        |                             |                     |   |   |                                     |                         |   |                        |                                 |   |                                 |  |
| Terminal Plating / Grid Array Ma   | aterial 7  | al Terminal Base Alloy |                             | -STD-020 MSL Rating |   | Peak Process Body Temperatu   |                                     | emperature              | ure Max Time at Peak Temper                   |                        | ture Num                        | ber of Reflow Cyc                         | les                             |  |
| Matte Tin (Sn) - annealed CU Alloy   |  |                        | 1                           |                     | 260   |   | С                                   | 30                      | seco  | nds 3                  |                                 |   |                                 |  |
| omments  |  |                        |                             |                     |   |   |                                     |                         |   |                        |                                 |   |                                 |  |
| vel 1 - maximum time at peak temperatu                                     | ire during so  | ldering is 10-3        | 0 seconds                   |                     |   |   |                                     |                         |   |                        |                                 |   |                                 |  |
| or more information regarding material                                     | composition  | please refer to        | page 3                      |                     |   |   |                                     |                         |   |                        |                                 |   |                                 |  |

| RoHS Material Composition Declaration  |  |   |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|---|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chror   | HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies  | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above  | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above  | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |   |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |   |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th   | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le  |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS        | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------|--------|--------|-----------------|
| Die                  | 0.147  | mg              | Supplier | Silicon (Si)               | 7440-21-3  |        | 0.147  | mg              |
| Die Attach Epoxy     | 0.04   | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.0368 | mg              |
|                      |        |                 | Supplier | Phenolic Resin-2           | 54208-63-8 |        | 0.0032 | mg              |
| Lead Frame           | 2.213  | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.0066 | mg              |
|                      |        |                 | Supplier | Zinc (Zn)                  | 7440-66-6  |        | 0.0027 | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6  |        | 0.052  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 2.151  | mg              |
|                      |        |                 | Supplier | Phosphorus (P)             | 7723-14-0  |        | 0.0007 | mg              |
| Mold Compound-Black  | 3.182  | mg              | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 |        | 0.9228 | mg              |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4  |        | 0.0318 | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0 |        | 2.2274 | mg              |
| Plating              | 0.23   | mg              | Supplier | Tin (Sn)                   | 7440-31-5  |        | 0.23   | mg              |
| Wire Bond - Au       | 0.03   | mg              | Supplier | Gold (Au)                  | 7440-57-5  |        | 0.03   | mg              |